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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "[Embedded - Microcontrollers](#)"

##### Details

Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	20
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.85V ~ 3.8V
Data Converters	A/D 24x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (Tj)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/silicon-labs/efm32jg1b100f256im32-c0r">https://www.e-xfl.com/product-detail/silicon-labs/efm32jg1b100f256im32-c0r</a>

### 3. System Overview

#### 3.1 Introduction

The EFM32JG1 product family is well suited for any battery operated application as well as other systems requiring high performance and low energy consumption. This section gives a short introduction to the MCU system. The detailed functional description can be found in the EFM32JG1 Reference Manual.

A block diagram of the EFM32JG1 family is shown in [Figure 3.1 Detailed EFM32JG1 Block Diagram on page 3](#). The diagram shows a superset of features available on the family, which vary by OPN. For more information about specific device features, consult [Ordering Information](#).

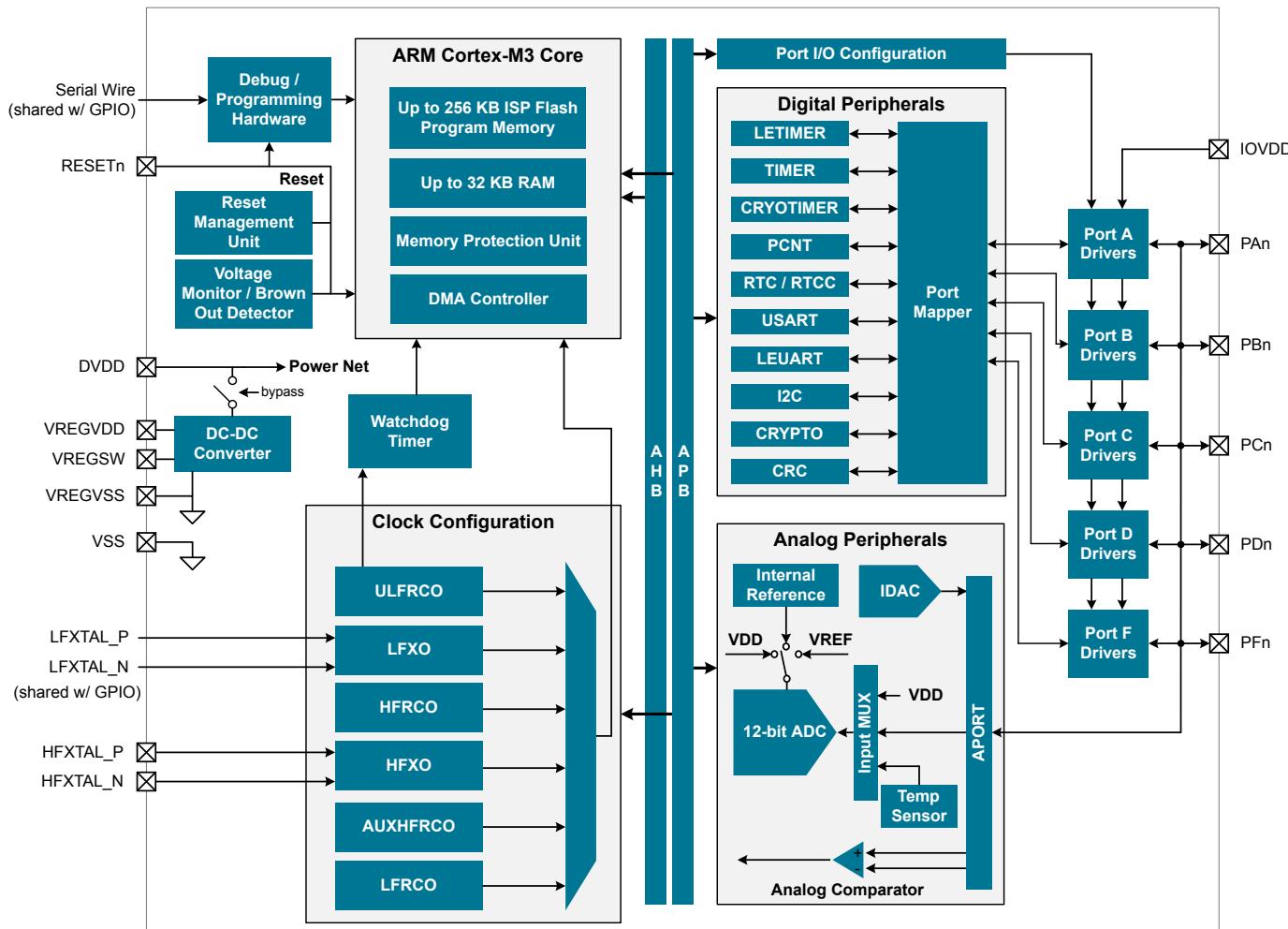
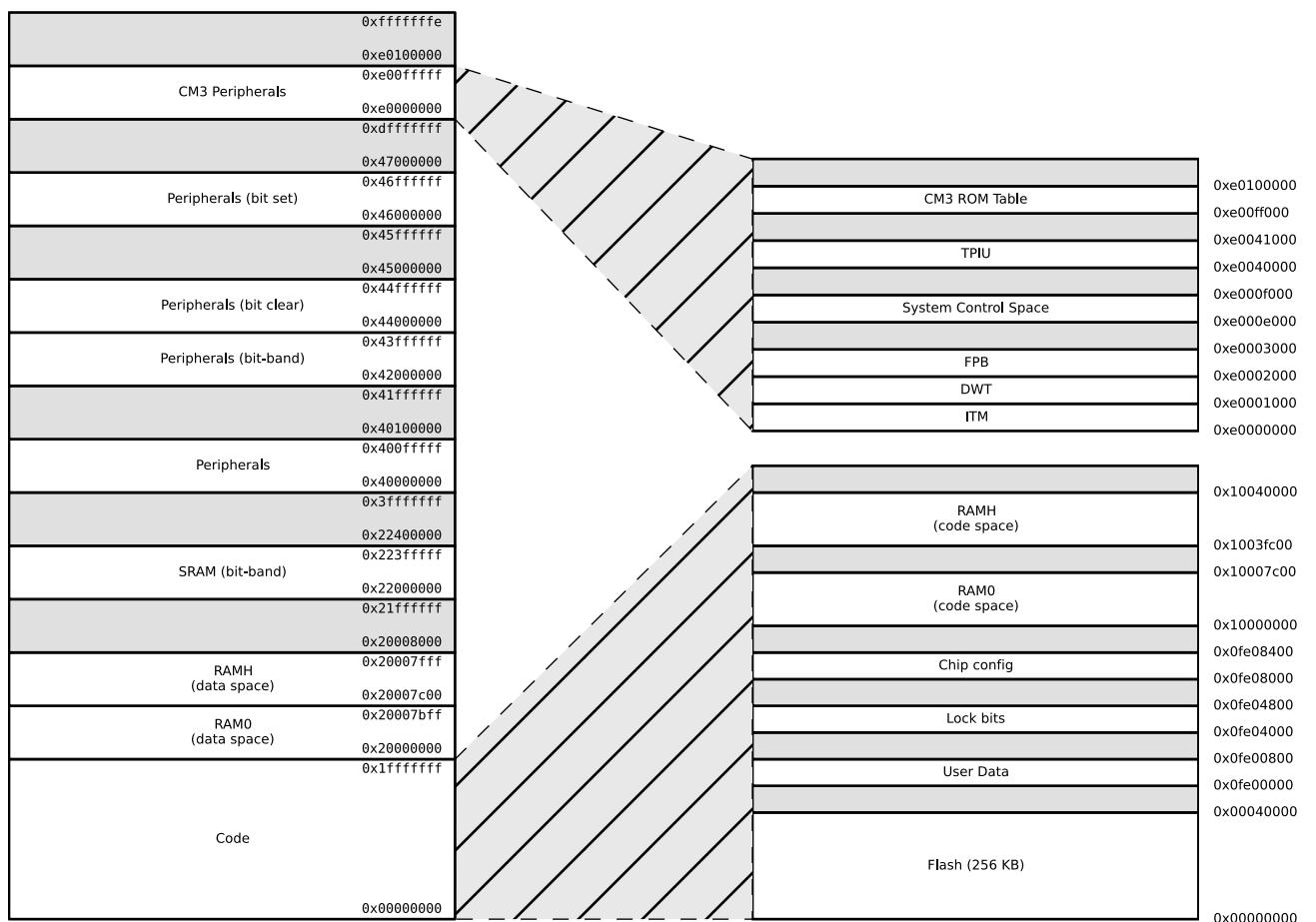


Figure 3.1. Detailed EFM32JG1 Block Diagram

### 3.11 Memory Map

The EFM32JG1 memory map is shown in the figures below. RAM and flash sizes are for the largest memory configuration.



**Figure 3.2. EFM32JG1 Memory Map — Core Peripherals and Code Space**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Max load current	I <sub>LOAD_MAX</sub>	Low noise (LN) mode, Heavy Drive <sup>4</sup> , T <sub>amb</sub> ≤ 85 °C	—	—	200	mA
		Low noise (LN) mode, Heavy Drive <sup>4</sup> , T <sub>amb</sub> > 85 °C	—	—	100	mA
		Low noise (LN) mode, Medium Drive <sup>4</sup>	—	—	100	mA
		Low noise (LN) mode, Light Drive <sup>4</sup>	—	—	50	mA
		Low power (LP) mode, LPCMPBIAS <sup>3</sup> = 0	—	—	75	µA
		Low power (LP) mode, LPCMPBIAS <sup>3</sup> = 3	—	—	10	mA
DCDC nominal output capacitor	C <sub>DCDC</sub>	25% tolerance	1	1	1	µF
DCDC nominal output inductor	L <sub>DCDC</sub>	20% tolerance	4.7	4.7	4.7	µH
Resistance in Bypass mode	R <sub>BYP</sub>		—	1.2	2.5	Ω

**Note:**

1. Due to internal dropout, the DC-DC output will never be able to reach its input voltage, V<sub>VREGVDD</sub>
2. LP mode controller is a hysteretic controller that maintains the output voltage within the specified limits
3. In EMU\_DCDCMISCCTRL register
4. Drive levels are defined by configuration of the PFETCNT and NFETCNT registers. Light Drive: PFETCNT=NFETCNT=3; Medium Drive: PFETCNT=NFETCNT=7; Heavy Drive: PFETCNT=NFETCNT=15.

#### 4.1.6 Wake up times

**Table 4.8. Wake up times**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Wake up from EM2 Deep Sleep	$t_{EM2\_WU}$	Code execution from flash	—	10.7	—	μs
		Code execution from RAM	—	3	—	μs
Wakeup time from EM1 Sleep	$t_{EM1\_WU}$	Executing from flash	—	3	—	AHB Clocks
		Executing from RAM	—	3	—	AHB Clocks
Wake up from EM3 Stop	$t_{EM3\_WU}$	Executing from flash	—	10.7	—	μs
		Executing from RAM	—	3	—	μs
Wake up from EM4H Hibernate <sup>1</sup>	$t_{EM4H\_WU}$	Executing from flash	—	60	—	μs
Wake up from EM4S Shut-off <sup>1</sup>	$t_{EM4S\_WU}$		—	290	—	μs
<b>Note:</b>						
1. Time from wakeup request until first instruction is executed. Wakeup results in device reset.						

#### 4.1.7 Brown Out Detector

**Table 4.9. Brown Out Detector**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
DVDBOD threshold	$V_{DVDBOD}$	DVDD rising	—	—	1.62	V
		DVDD falling	1.35	—	—	V
DVDD BOD hysteresis	$V_{DVDBOD\_HYST}$		—	24	—	mV
DVDD response time	$t_{DVDBOD\_DELAY}$	Supply drops at 0.1V/μs rate	—	2.4	—	μs
AVDD BOD threshold	$V_{AVDBOD}$	AVDD rising	—	—	1.85	V
		AVDD falling	1.62	—	—	V
AVDD BOD hysteresis	$V_{AVDBOD\_HYST}$		—	21	—	mV
AVDD response time	$t_{AVDBOD\_DELAY}$	Supply drops at 0.1V/μs rate	—	2.4	—	μs
EM4 BOD threshold	$V_{EM4DBOD}$	AVDD rising	—	—	1.7	V
		AVDD falling	1.45	—	—	V
EM4 BOD hysteresis	$V_{EM4BOD\_HYST}$		—	46	—	mV
EM4 response time	$t_{EM4BOD\_DELAY}$	Supply drops at 0.1V/μs rate	—	300	—	μs

#### 4.1.8 Oscillators

##### 4.1.8.1 LFXO

**Table 4.10. LFXO**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Crystal frequency	$f_{LFXO}$		—	32.768	—	kHz
Supported crystal equivalent series resistance (ESR)	$ESR_{LFXO}$		—	—	70	kΩ
Supported range of crystal load capacitance <sup>1</sup>	$C_{LFXO\_CL}$		6	—	18	pF
On-chip tuning cap range <sup>2</sup>	$C_{LFXO\_T}$	On each of LFXTAL_N and LFXTAL_P pins	8	—	40	pF
On-chip tuning cap step size	$SS_{LFXO}$		—	0.25	—	pF
Current consumption after startup <sup>3</sup>	$I_{LFXO}$	$ESR = 70 \text{ k}\Omega, C_L = 7 \text{ pF}, GAIN^4 = 3, AGC^4 = 1$	—	273	—	nA
Start-up time	$t_{LFXO}$	$ESR=70 \text{ k}\Omega, C_L = 7 \text{ pF}, GAIN^4 = 2$	—	308	—	ms

**Note:**

1. Total load capacitance as seen by the crystal
2. The effective load capacitance seen by the crystal will be  $C_{LFXO\_T} / 2$ . This is because each XTAL pin has a tuning cap and the two caps will be seen in series by the crystal.
3. Block is supplied by AVDD if ANASW = 0, or DVDD if ANASW=1 in EMU\_PWRCTRL register
4. In CMU\_LFXOCTRL register

**4.1.8.4 HFRCO and AUXHFRCO****Table 4.13. HFRCO and AUXHFRCO**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frequency Accuracy	$f_{HFRCO\_ACC}$	Any frequency band, across supply voltage and temperature	-2.5	—	2.5	%
Start-up time	$t_{HFRCO}$	$f_{HFRCO} \geq 19 \text{ MHz}$	—	300	—	ns
		$4 < f_{HFRCO} < 19 \text{ MHz}$	—	1	—	$\mu\text{s}$
		$f_{HFRCO} \leq 4 \text{ MHz}$	—	2.5	—	$\mu\text{s}$
Current consumption on all supplies	$I_{HFRCO}$	$f_{HFRCO} = 38 \text{ MHz}$	—	204	228	$\mu\text{A}$
		$f_{HFRCO} = 32 \text{ MHz}$	—	171	190	$\mu\text{A}$
		$f_{HFRCO} = 26 \text{ MHz}$	—	147	164	$\mu\text{A}$
		$f_{HFRCO} = 19 \text{ MHz}$	—	126	138	$\mu\text{A}$
		$f_{HFRCO} = 16 \text{ MHz}$	—	110	120	$\mu\text{A}$
		$f_{HFRCO} = 13 \text{ MHz}$	—	100	110	$\mu\text{A}$
		$f_{HFRCO} = 7 \text{ MHz}$	—	81	91	$\mu\text{A}$
		$f_{HFRCO} = 4 \text{ MHz}$	—	33	35	$\mu\text{A}$
		$f_{HFRCO} = 2 \text{ MHz}$	—	31	35	$\mu\text{A}$
		$f_{HFRCO} = 1 \text{ MHz}$	—	30	35	$\mu\text{A}$
Step size	$SS_{HFRCO}$	Coarse (% of period)	—	0.8	—	%
		Fine (% of period)	—	0.1	—	%
Period Jitter	$PJ_{HFRCO}$		—	0.2	—	% RMS

**4.1.8.5 ULFRCO****Table 4.14. ULFRCO**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency	$f_{ULFRCO}$		0.95	1	1.07	kHz

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Note:</b>						
1.	PSRR	referenced to AVDD when ANASW=0 and to DVDD when ANASW=1 in EMU_PWRCTRL				
2.	In ADCn_CNTL register					
3.	In ADCn_BIASPROG register					
4.	Derived from ADCCLK					

## 4.1.14 Analog Comparator (ACMP)

Table 4.20. ACMP

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V <sub>ACMPIN</sub>	ACMPVDD = ACMPn_CTRL_PWRSEL <sup>1</sup>	0	—	V <sub>ACMPVDD</sub>	V
Supply Voltage	V <sub>ACMPVDD</sub>	BIASPROG <sup>2</sup> ≤ 0x10 or FULL-BIAS <sup>2</sup> = 0	1.85	—	V <sub>VREGVDD_MAX</sub>	V
		0x10 < BIASPROG <sup>2</sup> ≤ 0x20 and FULLBIAS <sup>2</sup> = 1	2.1	—	V <sub>VREGVDD_MAX</sub>	V
Active current not including voltage reference	I <sub>ACMP</sub>	BIASPROG <sup>2</sup> = 1, FULLBIAS <sup>2</sup> = 0	—	50	—	nA
		BIASPROG <sup>2</sup> = 0x10, FULLBIAS <sup>2</sup> = 0	—	306	—	nA
		BIASPROG <sup>2</sup> = 0x20, FULLBIAS <sup>2</sup> = 1	—	74	95	μA
Current consumption of internal voltage reference	I <sub>ACMPREF</sub>	VLP selected as input using 2.5 V Reference / 4 (0.625 V)	—	50	—	nA
		VLP selected as input using VDD	—	20	—	nA
		VBDIV selected as input using 1.25 V reference / 1	—	4.1	—	μA
		VADIV selected as input using VDD/1	—	2.4	—	μA
Hysteresis (V <sub>CM</sub> = 1.25 V, BIASPROG <sup>2</sup> = 0x10, FULL-BIAS <sup>2</sup> = 1)	V <sub>ACMPHYST</sub>	HYSTSEL <sup>3</sup> = HYST0	-1.75	0	1.75	mV
		HYSTSEL <sup>3</sup> = HYST1	10	18	26	mV
		HYSTSEL <sup>3</sup> = HYST2	21	32	46	mV
		HYSTSEL <sup>3</sup> = HYST3	27	44	63	mV
		HYSTSEL <sup>3</sup> = HYST4	32	55	80	mV
		HYSTSEL <sup>3</sup> = HYST5	38	65	100	mV
		HYSTSEL <sup>3</sup> = HYST6	43	77	121	mV
		HYSTSEL <sup>3</sup> = HYST7	47	86	148	mV
		HYSTSEL <sup>3</sup> = HYST8	-4	0	4	mV
		HYSTSEL <sup>3</sup> = HYST9	-27	-18	-10	mV
		HYSTSEL <sup>3</sup> = HYST10	-47	-32	-18	mV
		HYSTSEL <sup>3</sup> = HYST11	-64	-43	-27	mV
		HYSTSEL <sup>3</sup> = HYST12	-78	-54	-32	mV
		HYSTSEL <sup>3</sup> = HYST13	-93	-64	-37	mV
		HYSTSEL <sup>3</sup> = HYST14	-113	-74	-42	mV
		HYSTSEL <sup>3</sup> = HYST15	-135	-85	-47	mV

**I2C Fast-mode Plus (Fm+)****Table 4.23. I2C Fast-mode Plus (Fm+)<sup>1</sup>**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency <sup>2</sup>	$f_{SCL}$		0	—	1000	kHz
SCL clock low time	$t_{LOW}$		0.5	—	—	$\mu s$
SCL clock high time	$t_{HIGH}$		0.26	—	—	$\mu s$
SDA set-up time	$t_{SU,DAT}$		50	—	—	ns
SDA hold time	$t_{HD,DAT}$		100	—	—	ns
Repeated START condition set-up time	$t_{SU,STA}$		0.26	—	—	$\mu s$
(Repeated) START condition hold time	$t_{HD,STA}$		0.26	—	—	$\mu s$
STOP condition set-up time	$t_{SU,STO}$		0.26	—	—	$\mu s$
Bus free time between a STOP and START condition	$t_{BUF}$		0.5	—	—	$\mu s$

**Note:**

1. For CLHR set to 0 or 1 in the I2Cn\_CTRL register
2. For the minimum HFPERCLK frequency required in Fast-mode Plus, refer to the I2C chapter in the reference manual

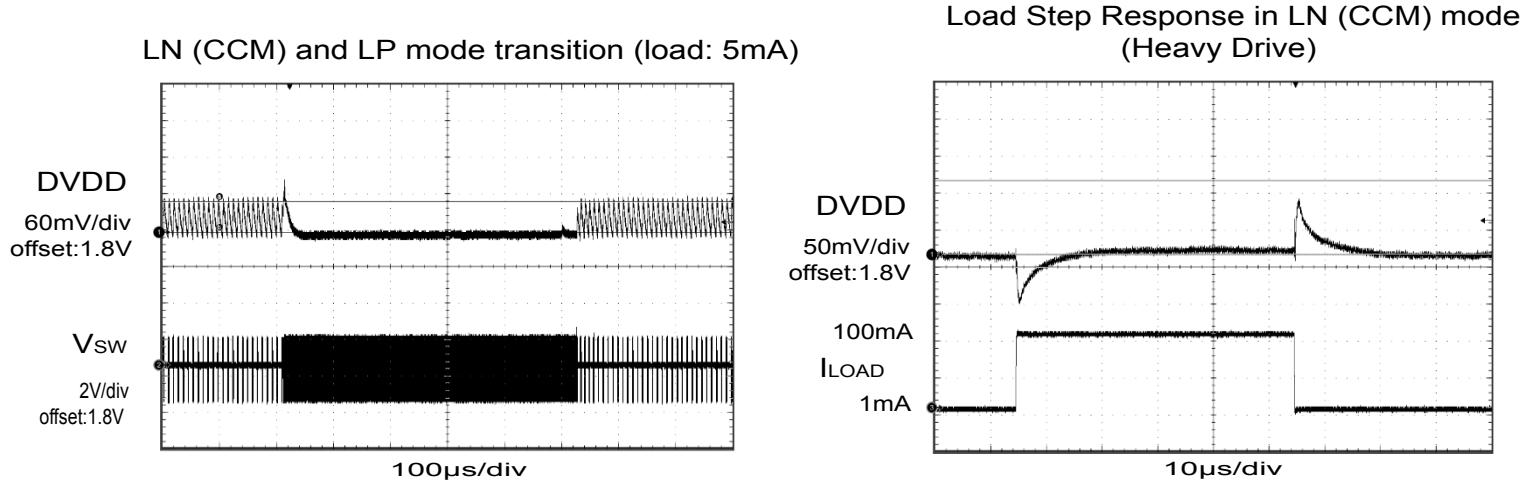


Figure 4.7. DC-DC Converter Transition Waveforms

#### 4.2.3 Internal Oscillators

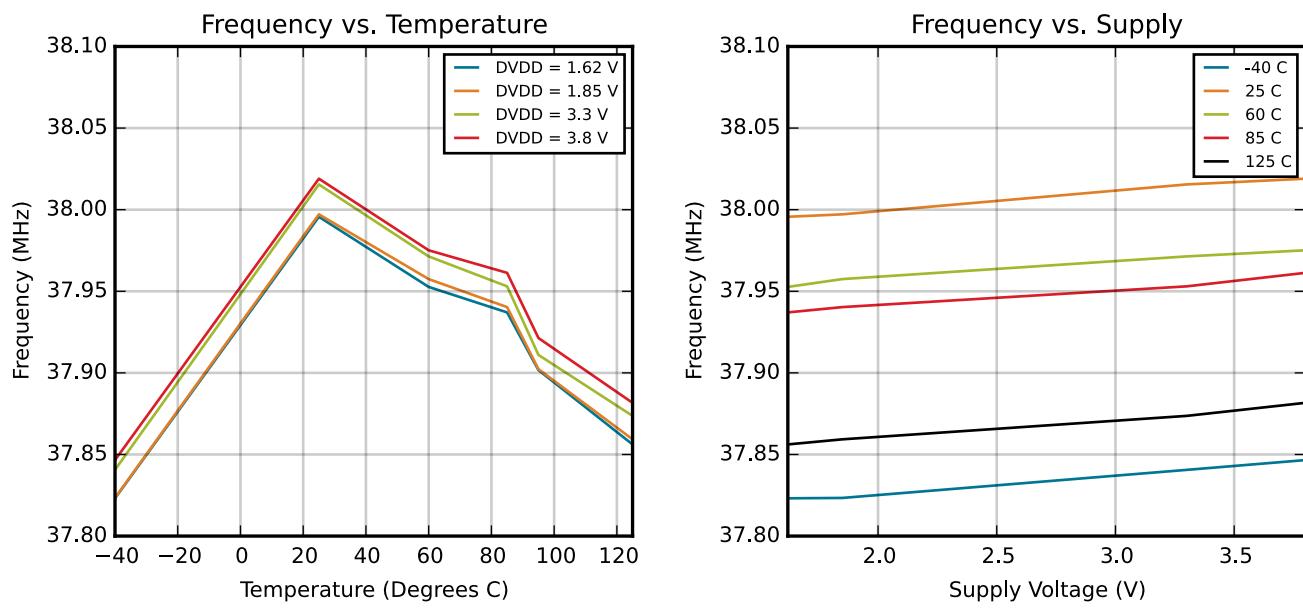


Figure 4.8. HFRCO and AUXHFRCO Typical Performance at 38 MHz

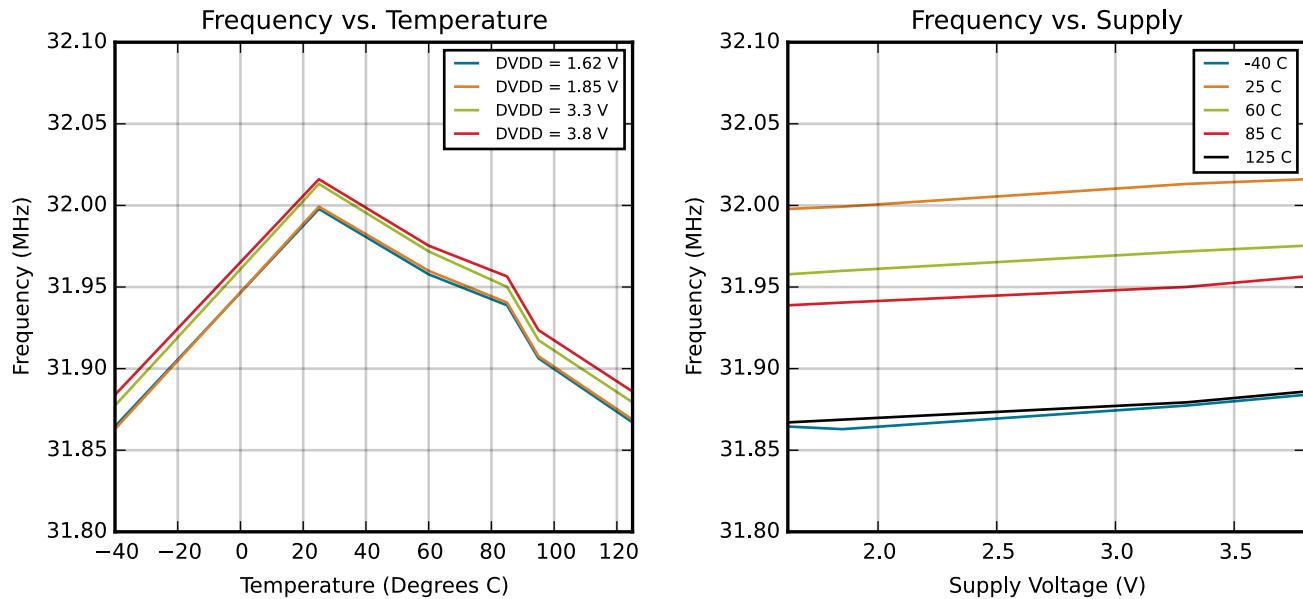


Figure 4.9. HFRCO and AUXHFRCO Typical Performance at 32 MHz

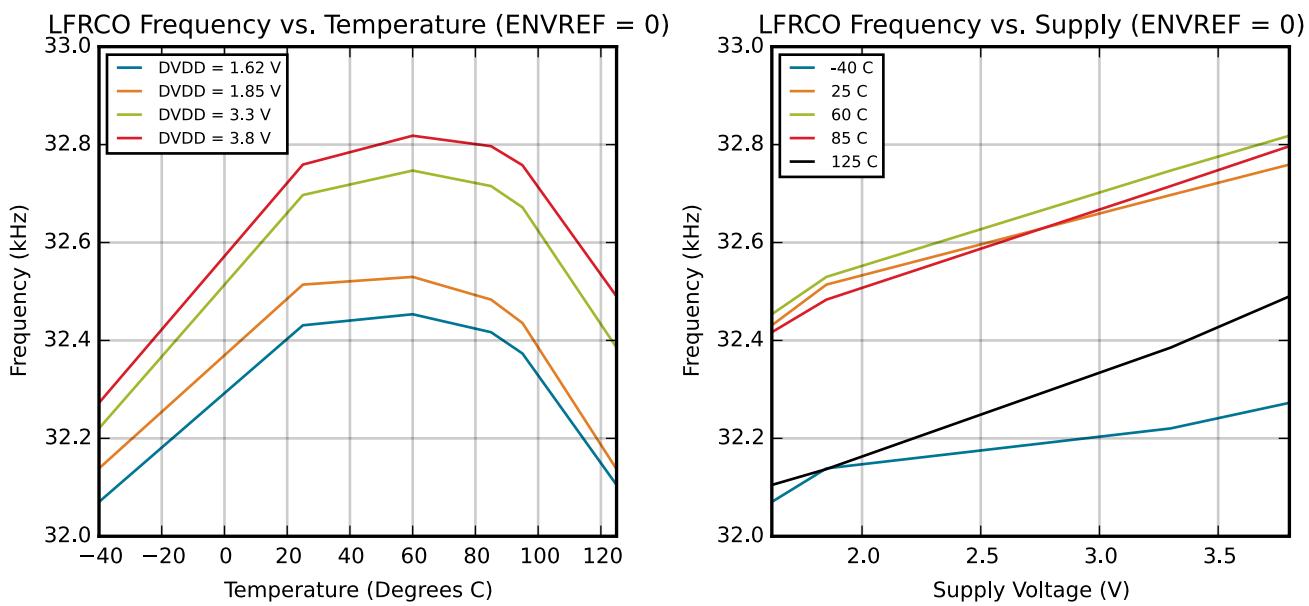


Figure 4.18. LFRCO Typical Performance at 32.768 kHz

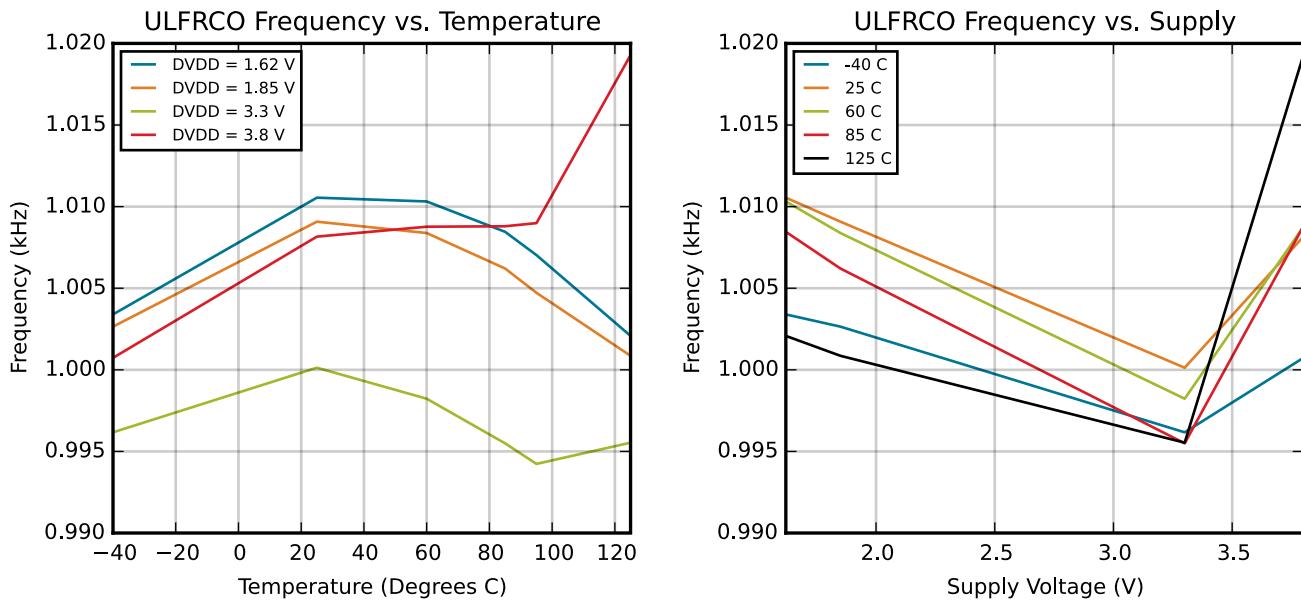


Figure 4.19. ULFRCO Typical Performance at 1 kHz

## 6. Pin Definitions

### 6.1 EFM32JG1 QFN48 with DC-DC Definition

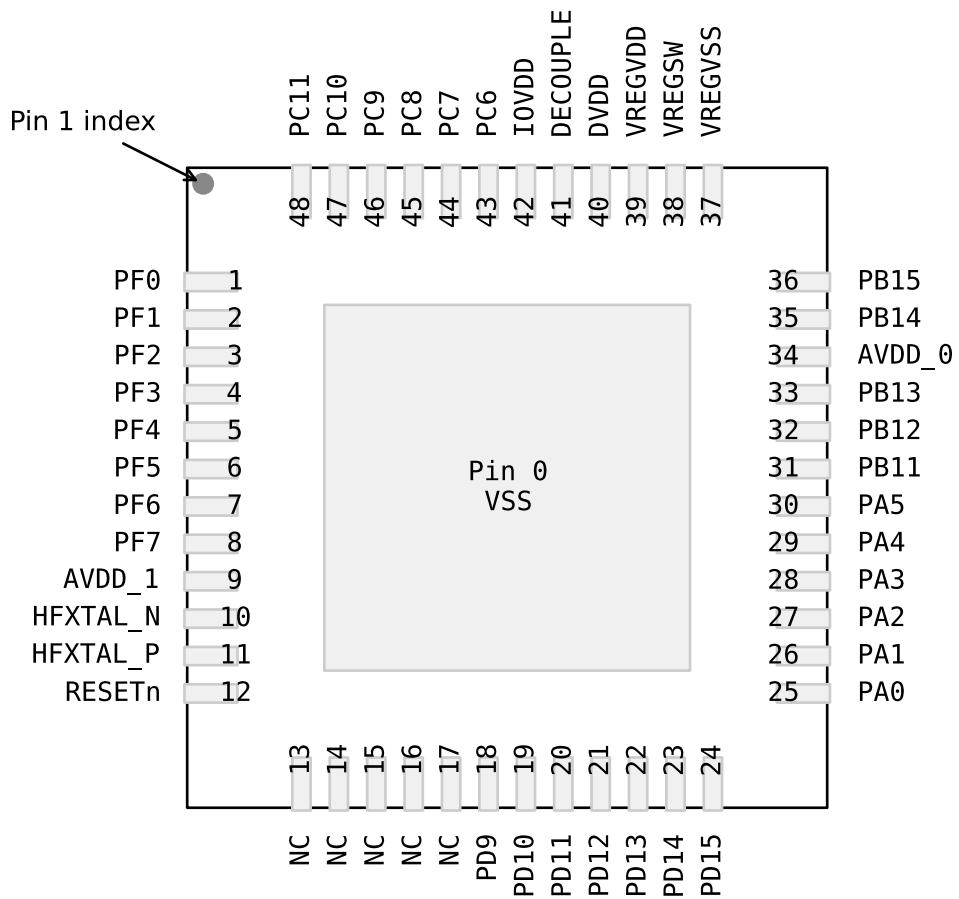


Figure 6.1. EFM32JG1 QFN48 with DC-DC Pinout

Table 6.1. QFN48 with DC-DC Device Pinout

QFN48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	RFVSS	Radio Ground			
1	PF0	BUSAX BUSBY	TIM0_CC0 #24 TIM0_CC1 #23 TIM0_CC2 #22 TIM0_CDTI0 #21 TIM0_CDTI1 #20 TIM0_CDTI2 #19 TIM1_CC0 #24 TIM1_CC1 #23 TIM1_CC2 #22 TIM1_CC3 #21 LE- TIM0_OUT0 #24 LE- TIM0_OUT1 #23 PCNT0_S0IN #24 PCNT0_S1IN #23	US0_TX #24 US0_RX #23 US0_CLK #22 US0_CS #21 US0_CTS #20 US0_RTS #19 US1_TX #24 US1_RX #23 US1_CLK #22 US1_CS #21 US1_CTS #20 US1_RTS #19 LEU0_TX #24 LEU0_RX #23 I2C0_SDA #24 I2C0_SCL #23	PRS_CH0 #0 PRS_CH1 #7 PRS_CH2 #6 PRS_CH3 #5 ACMP0_O #24 ACMP1_O #24 DBG_SWCLKTCK #0 BOOT_TX
2	PF1	BUSAY BUSBX	TIM0_CC0 #25 TIM0_CC1 #24 TIM0_CC2 #23 TIM0_CDTI0 #22 TIM0_CDTI1 #21 TIM0_CDTI2 #20 TIM1_CC0 #25 TIM1_CC1 #24 TIM1_CC2 #23 TIM1_CC3 #22 LE- TIM0_OUT0 #25 LE- TIM0_OUT1 #24 PCNT0_S0IN #25 PCNT0_S1IN #24	US0_TX #25 US0_RX #24 US0_CLK #23 US0_CS #22 US0_CTS #21 US0_RTS #20 US1_TX #25 US1_RX #24 US1_CLK #23 US1_CS #22 US1_CTS #21 US1_RTS #20 LEU0_TX #25 LEU0_RX #24 I2C0_SDA #25 I2C0_SCL #24	PRS_CH0 #1 PRS_CH1 #0 PRS_CH2 #7 PRS_CH3 #6 ACMP0_O #25 ACMP1_O #25 DBG_SWDIOTMS #0 BOOT_RX
3	PF2	BUSAX BUSBY	TIM0_CC0 #26 TIM0_CC1 #25 TIM0_CC2 #24 TIM0_CDTI0 #23 TIM0_CDTI1 #22 TIM0_CDTI2 #21 TIM1_CC0 #26 TIM1_CC1 #25 TIM1_CC2 #24 TIM1_CC3 #23 LE- TIM0_OUT0 #26 LE- TIM0_OUT1 #25 PCNT0_S0IN #26 PCNT0_S1IN #25	US0_TX #26 US0_RX #25 US0_CLK #24 US0_CS #23 US0_CTS #22 US0_RTS #21 US1_TX #26 US1_RX #25 US1_CLK #24 US1_CS #23 US1_CTS #22 US1_RTS #21 LEU0_TX #26 LEU0_RX #25 I2C0_SDA #26 I2C0_SCL #25	CMU_CLK0 #6 PRS_CH0 #2 PRS_CH1 #1 PRS_CH2 #0 PRS_CH3 #7 ACMP0_O #26 ACMP1_O #26 DBG_TDO #0 DBG_SWO #0 GPIO_EM4WU0

QFN48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
8	PF7	BUSAY BUSBX	TIM0_CC0 #31 TIM0_CC1 #30 TIM0_CC2 #29 TIM0_CDTI0 #28 TIM0_CDTI1 #27 TIM0_CDTI2 #26 TIM1_CC0 #31 TIM1_CC1 #30 TIM1_CC2 #29 TIM1_CC3 #28 LE- TIM0_OUT0 #31 LE- TIM0_OUT1 #30 PCNT0_S0IN #31 PCNT0_S1IN #30	US0_TX #31 US0_RX #30 US0_CLK #29 US0_CS #28 US0_CTS #27 US0_RTS #26 US1_TX #31 US1_RX #30 US1_CLK #29 US1_CS #28 US1_CTS #27 US1_RTS #26 LEU0_TX #31 LEU0_RX #30 I2C0_SDA #31 I2C0_SCL #30	CMU_CLK0 #7 PRS_CH0 #7 PRS_CH1 #6 PRS_CH2 #5 PRS_CH3 #4 ACMP0_O #31 ACMP1_O #31 GPIO_EM4WU1
9	AVDD	Analog power supply .			
10	HFXTAL_N	High Frequency Crystal input pin.			
11	HFXTAL_P	High Frequency Crystal output pin.			
12	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
13	NC	No Connect.			
14	NC	No Connect.			
15	NC	No Connect.			
16	NC	No Connect.			
17	NC	No Connect.			
18	PD9	BUSCY BUSDX	TIM0_CC0 #17 TIM0_CC1 #16 TIM0_CC2 #15 TIM0_CDTI0 #14 TIM0_CDTI1 #13 TIM0_CDTI2 #12 TIM1_CC0 #17 TIM1_CC1 #16 TIM1_CC2 #15 TIM1_CC3 #14 LE- TIM0_OUT0 #17 LE- TIM0_OUT1 #16 PCNT0_S0IN #17 PCNT0_S1IN #16	US0_TX #17 US0_RX #16 US0_CLK #15 US0_CS #14 US0_CTS #13 US0_RTS #12 US1_TX #17 US1_RX #16 US1_CLK #15 US1_CS #14 US1_CTS #13 US1_RTS #12 LEU0_TX #17 LEU0_RX #16 I2C0_SDA #17 I2C0_SCL #16	CMU_CLK0 #4 PRS_CH3 #8 PRS_CH4 #0 PRS_CH5 #6 PRS_CH6 #11 ACMP0_O #17 ACMP1_O #17
19	PD10	BUSCX BUSDY	TIM0_CC0 #18 TIM0_CC1 #17 TIM0_CC2 #16 TIM0_CDTI0 #15 TIM0_CDTI1 #14 TIM0_CDTI2 #13 TIM1_CC0 #18 TIM1_CC1 #17 TIM1_CC2 #16 TIM1_CC3 #15 LE- TIM0_OUT0 #18 LE- TIM0_OUT1 #17 PCNT0_S0IN #18 PCNT0_S1IN #17	US0_TX #18 US0_RX #17 US0_CLK #16 US0_CS #15 US0_CTS #14 US0_RTS #13 US1_TX #18 US1_RX #17 US1_CLK #16 US1_CS #15 US1_CTS #14 US1_RTS #13 LEU0_TX #18 LEU0_RX #17 I2C0_SDA #18 I2C0_SCL #17	CMU_CLK1 #4 PRS_CH3 #9 PRS_CH4 #1 PRS_CH5 #0 PRS_CH6 #12 ACMP0_O #18 ACMP1_O #18

QFN48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
24	PD15	BUSCY BUSDX	TIMO_CC0 #23 TIMO_CC1 #22 TIMO_CC2 #21 TIMO_CDTI0 #20 TIMO_CDTI1 #19 TIMO_CDTI2 #18 TIM1_CC0 #23 TIM1_CC1 #22 TIM1_CC2 #21 TIM1_CC3 #20 LE- TIMO_OUT0 #23 LE- TIMO_OUT1 #22 PCNT0_S0IN #23 PCNT0_S1IN #22	US0_TX #23 US0_RX #22 US0_CLK #21 US0_CS #20 US0_CTS #19 US0_RTS #18 US1_TX #23 US1_RX #22 US1_CLK #21 US1_CS #20 US1_CTS #19 US1_RTS #18 LEU0_TX #23 LEU0_RX #22 I2C0_SDA #23 I2C0_SCL #22	CMU_CLK1 #5 PRS_CH3 #14 PRS_CH4 #6 PRS_CH5 #5 PRS_CH6 #17 ACMP0_O #23 ACMP1_O #23 DBG_SWO #2
25	PA0	ADC0_EXTN BUSCX BUSDY	TIMO_CC0 #0 TIMO_CC1 #31 TIMO_CC2 #30 TIMO_CDTI0 #29 TIMO_CDTI1 #28 TIMO_CDTI2 #27 TIM1_CC0 #0 TIM1_CC1 #31 TIM1_CC2 #30 TIM1_CC3 #29 LE- TIMO_OUT0 #0 LE- TIMO_OUT1 #31 PCNT0_S0IN #0 PCNT0_S1IN #31	US0_TX #0 US0_RX #31 US0_CLK #30 US0_CS #29 US0_CTS #28 US0_RTS #27 US1_TX #0 US1_RX #31 US1_CLK #30 US1_CS #29 US1_CTS #28 US1_RTS #27 LEU0_TX #0 LEU0_RX #31 I2C0_SDA #0 I2C0_SCL #31	CMU_CLK1 #0 PRS_CH6 #0 PRS_CH7 #10 PRS_CH8 #9 PRS_CH9 #8 ACMP0_O #0 ACMP1_O #0
26	PA1	ADC0_EXTP BUSCY BUSDX	TIMO_CC0 #1 TIMO_CC1 #0 TIMO_CC2 #31 TIMO_CDTI0 #30 TIMO_CDTI1 #29 TIMO_CDTI2 #28 TIM1_CC0 #1 TIM1_CC1 #0 TIM1_CC2 #31 TIM1_CC3 #30 LE- TIMO_OUT0 #1 LE- TIMO_OUT1 #0 PCNT0_S0IN #1 PCNT0_S1IN #0	US0_TX #1 US0_RX #0 US0_CLK #31 US0_CS #30 US0_CTS #29 US0_RTS #28 US1_TX #1 US1_RX #0 US1_CLK #31 US1_CS #30 US1_CTS #29 US1_RTS #28 LEU0_RX #1 LEU0_RX #0 I2C0_SDA #1 I2C0_SCL #0	CMU_CLK0 #0 PRS_CH6 #1 PRS_CH7 #0 PRS_CH8 #10 PRS_CH9 #9 ACMP0_O #1 ACMP1_O #1
27	PA2	BUSCX BUSDY	TIMO_CC0 #2 TIMO_CC1 #1 TIMO_CC2 #0 TIMO_CDTI0 #31 TIMO_CDTI1 #30 TIMO_CDTI2 #29 TIM1_CC0 #2 TIM1_CC1 #1 TIM1_CC2 #0 TIM1_CC3 #31 LE- TIMO_OUT0 #2 LE- TIMO_OUT1 #1 PCNT0_S0IN #2 PCNT0_S1IN #1	US0_TX #2 US0_RX #1 US0_CLK #0 US0_CS #31 US0_CTS #30 US0_RTS #29 US1_TX #2 US1_RX #1 US1_CLK #0 US1_CS #31 US1_CTS #30 US1_RTS #29 LEU0_RX #2 LEU0_RX #1 I2C0_SDA #2 I2C0_SCL #1	PRS_CH6 #2 PRS_CH7 #1 PRS_CH8 #0 PRS_CH9 #10 ACMP0_O #2 ACMP1_O #2

QFN48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
46	PC9	BUSAY BUSBX	TIMO_CC0 #14 TIMO_CC1 #13 TIMO_CC2 #12 TIMO_CDTI0 #11 TIMO_CDTI1 #10 TIMO_CDTI2 #9 TIM1_CC0 #14 TIM1_CC1 #13 TIM1_CC2 #12 TIM1_CC3 #11 LE- Timo_OUT0 #14 LE- Timo_OUT1 #13 PCNT0_S0IN #14 PCNT0_S1IN #13	US0_TX #14 US0_RX #13 US0_CLK #12 US0_CS #11 US0_CTS #10 US0_RTS #9 US1_TX #14 US1_RX #13 US1_CLK #12 US1_CS #11 US1_CTS #10 US1_RTS #9 LEU0_TX #14 LEU0_RX #13 I2C0_SDA #14 I2C0_SCL #13	PRS_CH0 #11 PRS_CH9 #14 PRS_CH10 #3 PRS_CH11 #2 ACMP0_O #14 ACMP1_O #14
47	PC10	BUSAX BUSBY	TIMO_CC0 #15 TIMO_CC1 #14 TIMO_CC2 #13 TIMO_CDTI0 #12 TIMO_CDTI1 #11 TIMO_CDTI2 #10 TIM1_CC0 #15 TIM1_CC1 #14 TIM1_CC2 #13 TIM1_CC3 #12 LE- Timo_OUT0 #15 LE- Timo_OUT1 #14 PCNT0_S0IN #15 PCNT0_S1IN #14	US0_TX #15 US0_RX #14 US0_CLK #13 US0_CS #12 US0_CTS #11 US0_RTS #10 US1_TX #15 US1_RX #14 US1_CLK #13 US1_CS #12 US1_CTS #11 US1_RTS #10 LEU0_TX #15 LEU0_RX #14 I2C0_SDA #15 I2C0_SCL #14	CMU_CLK1 #3 PRS_CH0 #12 PRS_CH9 #15 PRS_CH10 #4 PRS_CH11 #3 ACMP0_O #15 ACMP1_O #15 GPIO_EM4WU12
48	PC11	BUSAY BUSBX	TIMO_CC0 #16 TIMO_CC1 #15 TIMO_CC2 #14 TIMO_CDTI0 #13 TIMO_CDTI1 #12 TIMO_CDTI2 #11 TIM1_CC0 #16 TIM1_CC1 #15 TIM1_CC2 #14 TIM1_CC3 #13 LE- Timo_OUT0 #16 LE- Timo_OUT1 #15 PCNT0_S0IN #16 PCNT0_S1IN #15	US0_TX #16 US0_RX #15 US0_CLK #14 US0_CS #13 US0_CTS #12 US0_RTS #11 US1_TX #16 US1_RX #15 US1_CLK #14 US1_CS #13 US1_CTS #12 US1_RTS #11 LEU0_TX #16 LEU0_RX #15 I2C0_SDA #16 I2C0_SCL #15	CMU_CLK0 #3 PRS_CH0 #13 PRS_CH9 #16 PRS_CH10 #5 PRS_CH11 #4 ACMP0_O #16 ACMP1_O #16 DBG_SWO #3

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
4	PF3	BUSAY BUSBX	TIM0_CC0 #27 TIM0_CC1 #26 TIM0_CC2 #25 TIM0_CDTI0 #24 TIM0_CDTI1 #23 TIM0_CDTI2 #22 TIM1_CC0 #27 TIM1_CC1 #26 TIM1_CC2 #25 TIM1_CC3 #24 LE- TIM0_OUT0 #27 LE- TIM0_OUT1 #26 PCNT0_S0IN #27 PCNT0_S1IN #26	US0_TX #27 US0_RX #26 US0_CLK #25 US0_CS #24 US0_CTS #23 US0_RTS #22 US1_TX #27 US1_RX #26 US1_CLK #25 US1_CS #24 US1_CTS #23 US1_RTS #22 LEU0_TX #27 LEU0_RX #26 I2C0_SDA #27 I2C0_SCL #26	CMU_CLK1 #6 PRS_CH0 #3 PRS_CH1 #2 PRS_CH2 #1 PRS_CH3 #0 ACMP0_O #27 ACMP1_O #27 DBG_TDI #0
5	AVDD	Analog power supply .			
6	HFXTAL_N	High Frequency Crystal input pin.			
7	HFXTAL_P	High Frequency Crystal output pin.			
8	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
9	NC	No Connect.			
10	PD9	BUSCY BUSDX	TIM0_CC0 #17 TIM0_CC1 #16 TIM0_CC2 #15 TIM0_CDTI0 #14 TIM0_CDTI1 #13 TIM0_CDTI2 #12 TIM1_CC0 #17 TIM1_CC1 #16 TIM1_CC2 #15 TIM1_CC3 #14 LE- TIM0_OUT0 #17 LE- TIM0_OUT1 #16 PCNT0_S0IN #17 PCNT0_S1IN #16	US0_TX #17 US0_RX #16 US0_CLK #15 US0_CS #14 US0_CTS #13 US0_RTS #12 US1_TX #17 US1_RX #16 US1_CLK #15 US1_CS #14 US1_CTS #13 US1_RTS #12 LEU0_TX #17 LEU0_RX #16 I2C0_SDA #17 I2C0_SCL #16	CMU_CLK0 #4 PRS_CH3 #8 PRS_CH4 #0 PRS_CH5 #6 PRS_CH6 #11 ACMP0_O #17 ACMP1_O #17
11	PD10	BUSCX BUSDY	TIM0_CC0 #18 TIM0_CC1 #17 TIM0_CC2 #16 TIM0_CDTI0 #15 TIM0_CDTI1 #14 TIM0_CDTI2 #13 TIM1_CC0 #18 TIM1_CC1 #17 TIM1_CC2 #16 TIM1_CC3 #15 LE- TIM0_OUT0 #18 LE- TIM0_OUT1 #17 PCNT0_S0IN #18 PCNT0_S1IN #17	US0_TX #18 US0_RX #17 US0_CLK #16 US0_CS #15 US0_CTS #14 US0_RTS #13 US1_TX #18 US1_RX #17 US1_CLK #16 US1_CS #15 US1_CTS #14 US1_RTS #13 LEU0_TX #18 LEU0_RX #17 I2C0_SDA #18 I2C0_SCL #17	CMU_CLK1 #4 PRS_CH3 #9 PRS_CH4 #1 PRS_CH5 #0 PRS_CH6 #12 ACMP0_O #18 ACMP1_O #18

## 7.2 QFN48 PCB Land Pattern

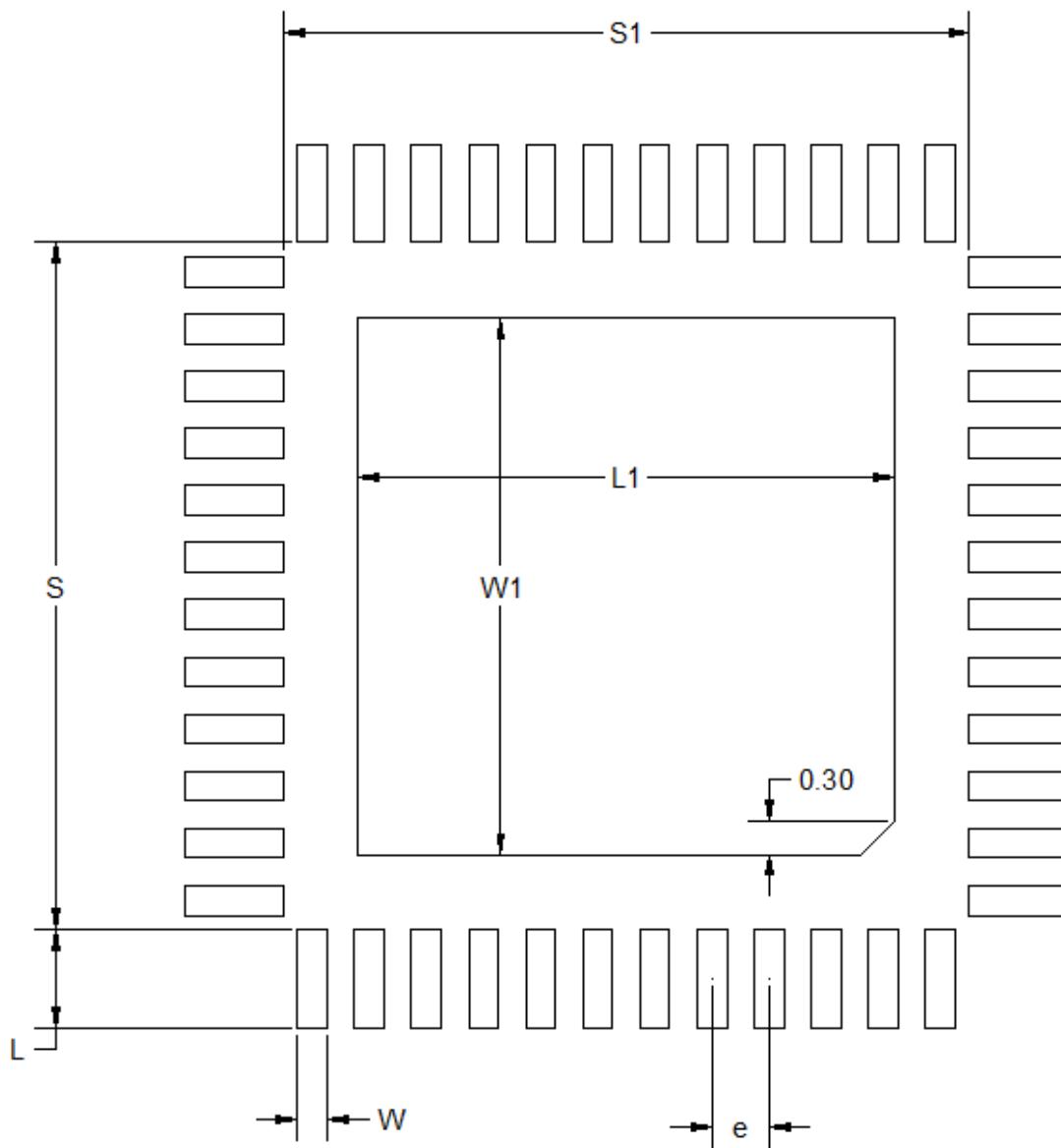


Figure 7.2. QFN48 PCB Land Pattern Drawing

**Table 7.2. QFN48 PCB Land Pattern Dimensions**

Dimension	Typ
S1	6.01
S	6.01
L1	4.70
W1	4.70
e	0.50
W	0.26
L	0.86

**Note:**

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.
3. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.
4. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
5. The stencil thickness should be 0.125 mm (5 mils).
6. The ratio of stencil aperture to land pad size can be 1:1 for all perimeter pads.
7. A 4x4 array of 0.75 mm square openings on a 1.00 mm pitch can be used for the center ground pad.
8. A No-Clean, Type-3 solder paste is recommended.
9. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.